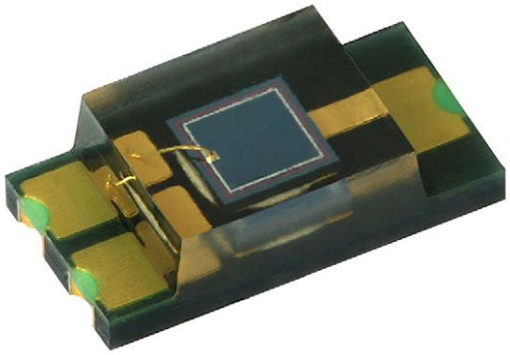
Silicon PIN Photodiode



FEATURES

- Package type: surface mount
- Package form: 1206
- Dimensions (L x W x H in mm): 4 x 2 x 1.05
- Radiant sensitive area (in mm^2): 0.85
- High photo sensitivity
- High radiant sensitivity
- Excellent I_{ra} linearity
- Suitable for visible and near infrared radiation
- Fast response times
- Angle of half sensitivity: φ = ± 70°
- Floor life: 72 h, MSL 4, according to J-STD-020
- Lead (Pb)-free reflow soldering
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

AUTOMOTIVE GRADE

Pb-free

e4

RoHS COMPLIANT

HALOGEN FREE

GREEN (5-2008)

DESCRIPTION

VEMD6060X01 is a high speed and high sensitive PIN photodiode with excellent I_{ra} linearity. It is a small surface mount device (SMD) including the chip with a 0.85 mm^2 sensitive area detecting visible and near infrared radiation.

APPLICATIONS

- High speed photo detector
- Small signal detection
- Proximity sensors

PRODUCT SUMMARY			
COMPONENT	**I_{ra} (µA)**	**φ (deg)**	**$\lambda_{0.1}$ (nm)**
VEMD6060X01	5	± 70	380 to 1070

Note

- Test conditions see table “Basic Characteristics”

ORDERING INFORMATION			
ORDERING CODE	**PACKAGING**	**REMARKS**	**PACKAGE FORM**
VEMD6060X01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	1206

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T_{amb} = 25 °C, unless otherwise specified)				
PARAMETER	**TEST CONDITION**	**SYMBOL**	**VALUE**	**UNIT**
Reverse voltage		V_R	20	V
Power dissipation	$T_{amb} \leq 25$ °C	P_V	215	mW
Junction temperature		T_j	110	°C
Operating temperature range		T_{amb}	-40 to +110	°C
Storage temperature range		T_{stg}	-40 to +110	°C
Soldering temperature	According to reflow solder profile fig. 8	T_{sd}	260	°C
Thermal resistance junction / ambient	According to EIA / JESD51	R_{thJA}	270	K/W

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)						
PARAMETER	**TEST CONDITION**	**SYMBOL**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Forward voltage	I_F = 50 mA	V_F	-	0.85	1.1	V
Breakdown voltage	I_R = 100 µA, E = 0	$V_{(BR)}$	20	-	-	V
Reverse dark current	V_R = 10 V, E = 0	I_{ro}	-	0.03	5	nA
Diode capacitance	V_R = 0 V, f = 1 MHz, E = 0	C_D	-	11	-	pF
	V_R = 5 V, f = 1 MHz, E = 0	C_D	-	4.8	-	pF
Open circuit voltage	E_e = 1 mW/cm², λ = 950 nm	V_o	-	360	-	mV
Temperature coefficient of V_o	E_e = 1 mW/cm², λ = 950 nm	TK_{Vo}	-	-3.1	-	mV/K
Short circuit current	E_e = 1 mW/cm², λ = 950 nm	I_k	-	5	-	µA
Temperature coefficient of I_k	E_e = 1 mW/cm², λ = 835 nm	TK_{Ik}	-	0.1	-	%/K
Reverse light current	E_e = 1 mW/cm², λ = 950 nm, V_R = 5 V	I_{ra}	3.5	5	6.5	µA
	E_e = 1 mW/cm², λ = 890 nm, V_R = 5 V	I_{ra}	-	7	-	µA
Angle of half sensitivity		φ	-	± 70	-	deg
Wavelength of peak sensitivity		$λ_p$	-	820	-	nm
Range of spectral bandwidth		$λ_{0.1}$	-	380 to 1070	-	nm
Rise time	V_R = 10 V, R_L = 50 Ω, λ = 830 nm	t_r	-	60	-	ns
Fall time	V_R = 10 V, R_L = 50 Ω, λ = 830 nm	t_f	-	50	-	ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

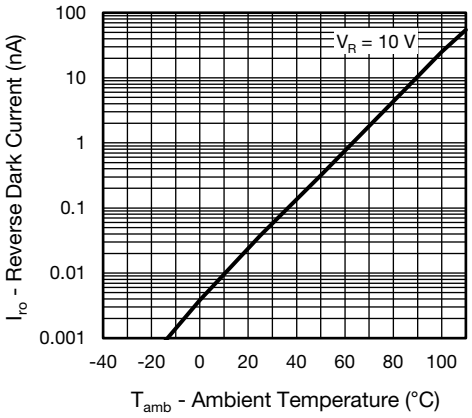


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

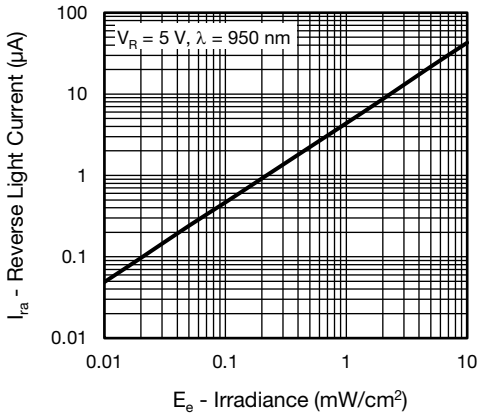


Fig. 3 - Reverse Light Current vs. Irradiance

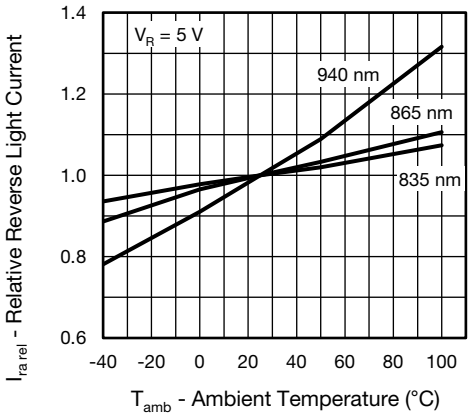


Fig. 2 - Relative Reverse Light Current vs. Ambient Temperature

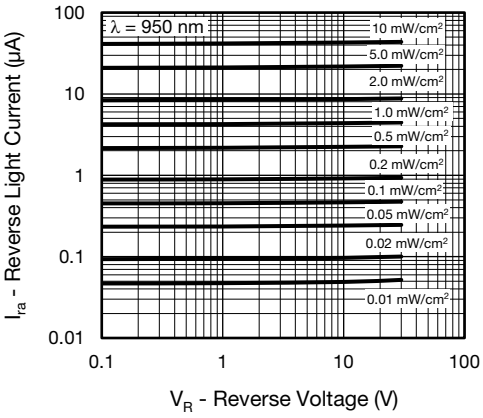


Fig. 4 - Reverse Light Current vs. Reverse Voltage

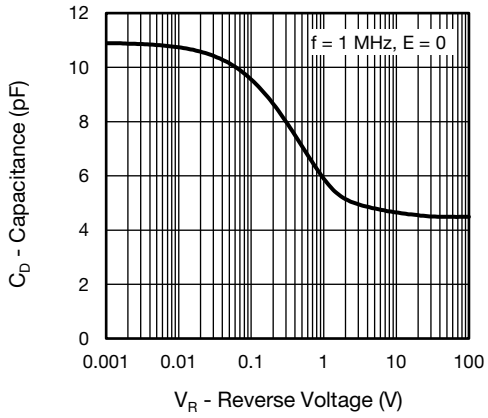


Fig. 5 - Diode Capacitance vs. Reverse Voltage

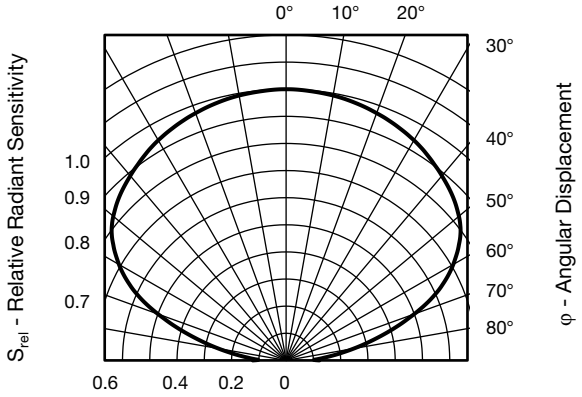


Fig. 7 - Relative Radiant Sensitivity vs. Angular Displacement

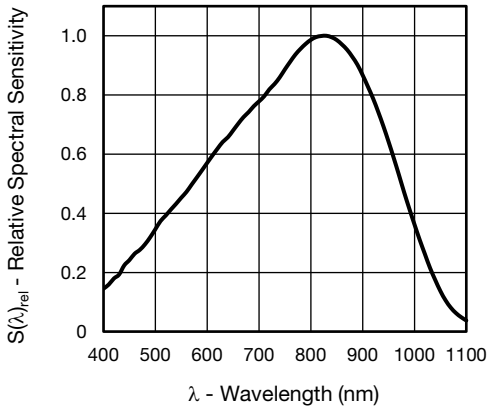


Fig. 6 - Relative Spectral Sensitivity vs. Wavelength

REFLOW SOLDER PROFILE

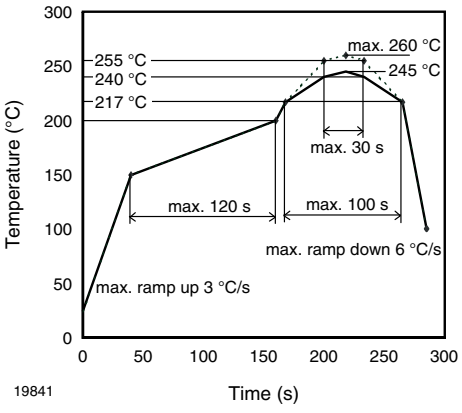


Fig. 8 - Lead (Pb)-free Reflow Solder Profile
According to J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 72 h

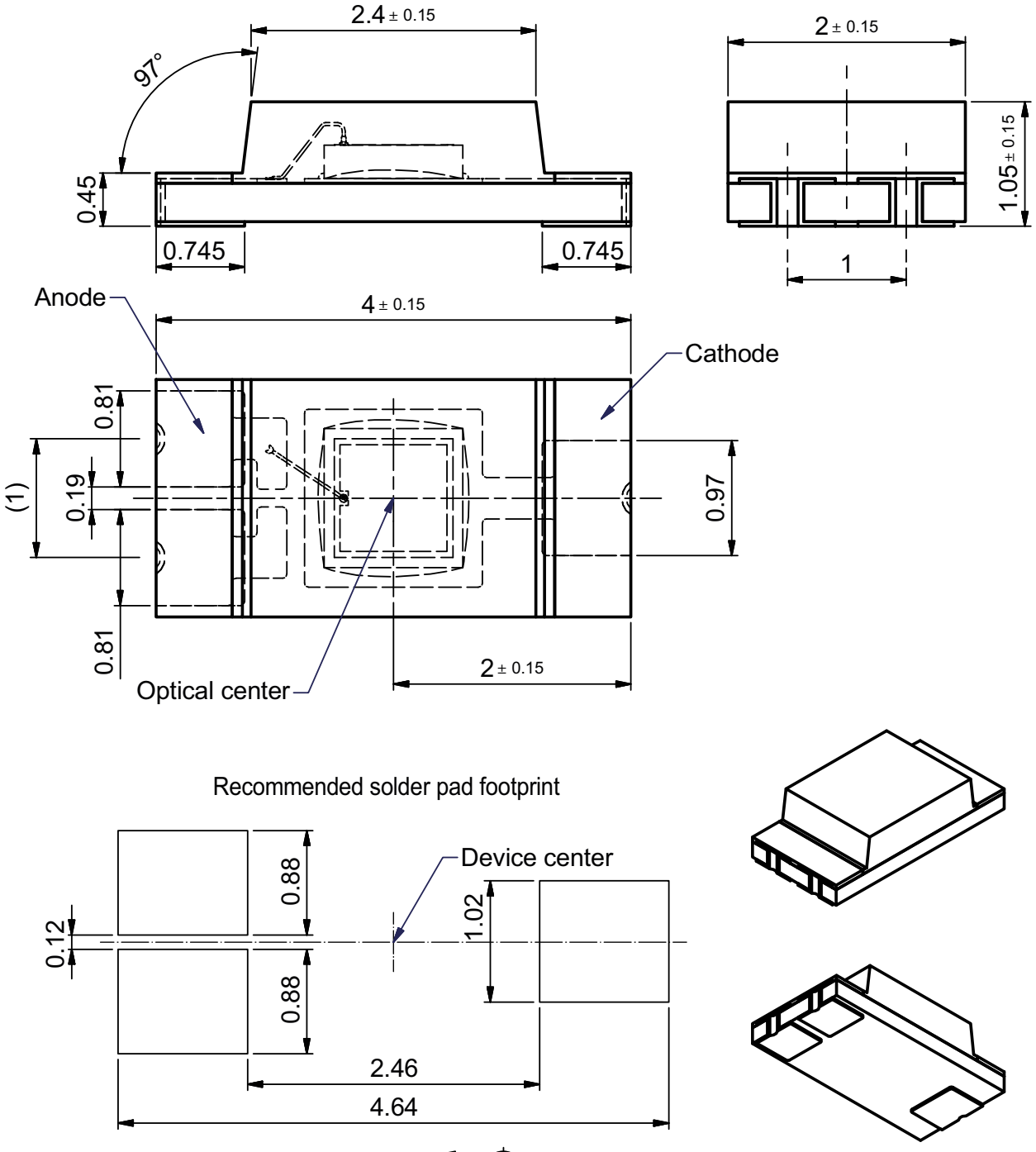
Conditions: T_{amb} < 30 °C, RH < 60 %

Moisture sensitivity level 4, according to J-STD-020.

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

PACKAGE DIMENSIONS in millimeters

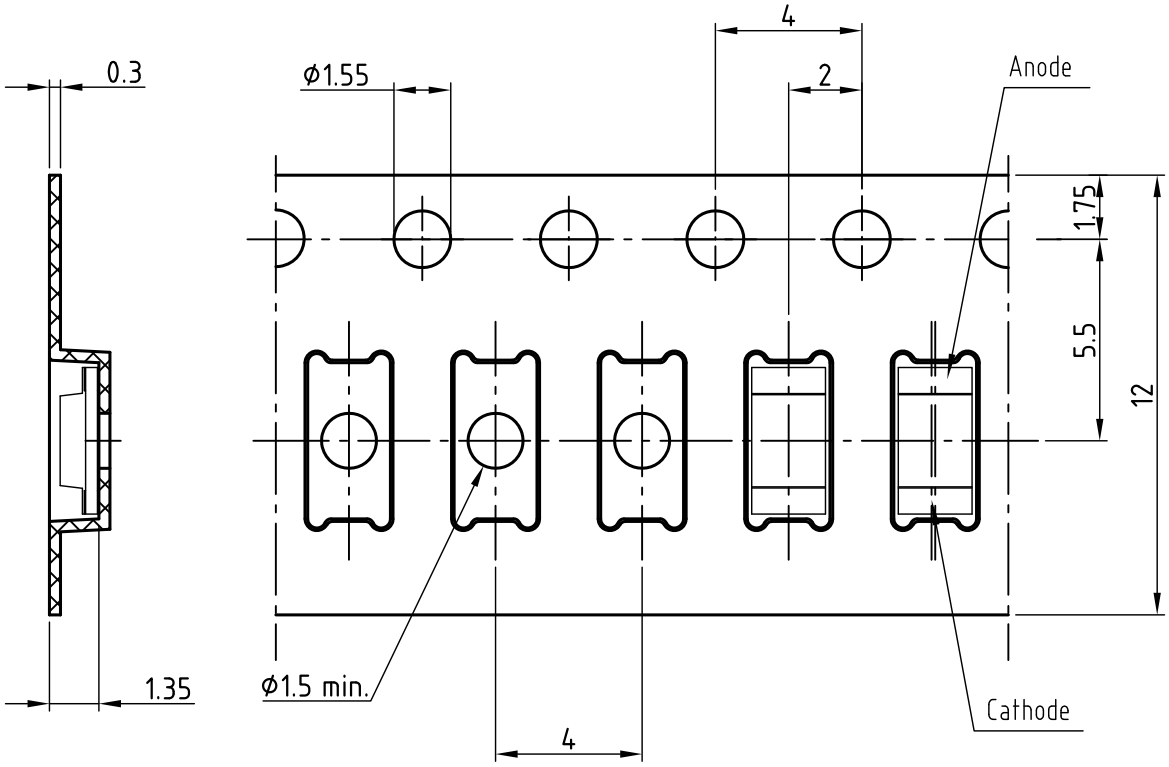


Drawing-No. 6.541-5100.01-4
Preliminary issue 04.07.2013

Technical drawings according to DIN specification.

Not indicated tolerances ± 0.1mm

BLISTER TAPE DIMENSIONS in millimeters



Reel off direction

technical drawings according to DIN specifications

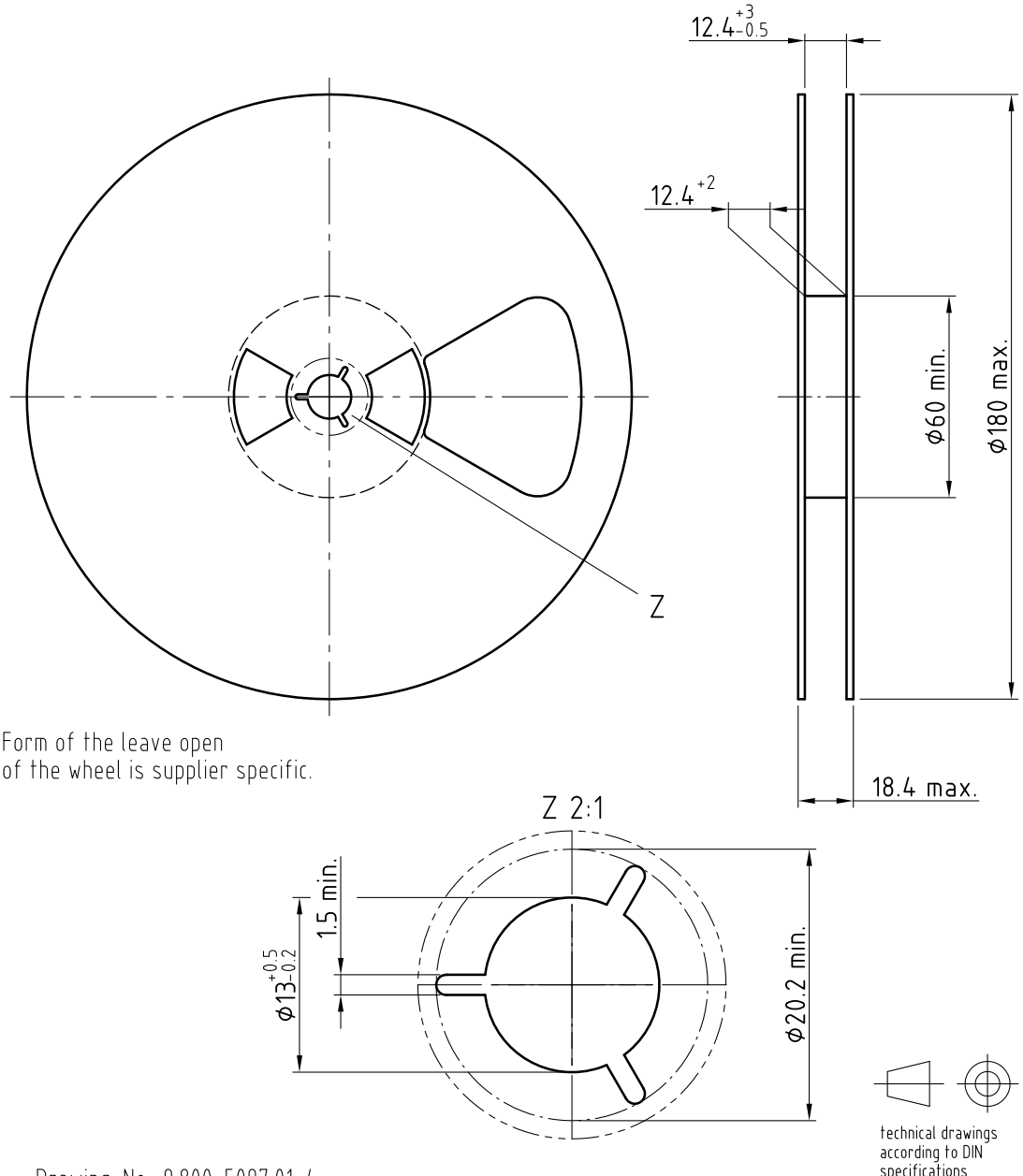
Not indicated tolerances ±0.1

All dimensions in mm

Drawing refers to following Types: TEMD6010FX01
VEMD6x10X01
VEMD6x15X01

Drawing-No.: 9.700-5329.02-4
Prel Issue: 16.07.2013

REEL DIMENSIONS in millimeters



Form of the leave open
of the wheel is supplier specific.

Drawing-No.: 9.800-5097.01-4
Issue: 1; 05.05.08

20874

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